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[54] AQUEOUS DISPERSION FOR CHEMICAL-MECHANICAL POLISHING

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[57] ABSTRACT

PROBLEM TO BE SOLVED: To prepare an aqueous dispersion desirably used for, especially, polishing semiconductors, having a high polishing rate, causing less erosion, and having excellent dispersion stability.

SOLUTION: This dispersion is obtained by adding to ion-exchanged water abrasive grains (fumed process alumina particles), an agglomeration accelerating particles, such as particles of a silica/alumina mixed crystal, having electrically positive parts and electrically negative parts within each particle and therefore having moderate electrically attracting force and being capable of agglomerating the abrasive grains, an oxidizing agent (e.g. ammonium persulfate), and the like, and agitating the mixture.

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